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(12) **United States Design Patent**
Lin et al.

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(45) **Date of Patent: ** Sep. 27, 2022**

(54) **HEAT SINK FOR MEMORY MODULE**

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(73) Assignee: **KINGSTON DIGITAL, INC.**, Fountain Valley, CA (US)

(**) Term: **15 Years**

(21) Appl. No.: **29/786,896**

(22) Filed: **Jun. 3, 2021**

(51) **LOC (13) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/179**; D14/435

(58) **Field of Classification Search**
USPC D13/179; D14/435
CPC ... F28F 2215/00; F28F 2215/08; H01L 23/40; H01L 23/367; H01L 23/4093
See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a heat sink for memory module, as shown and described.

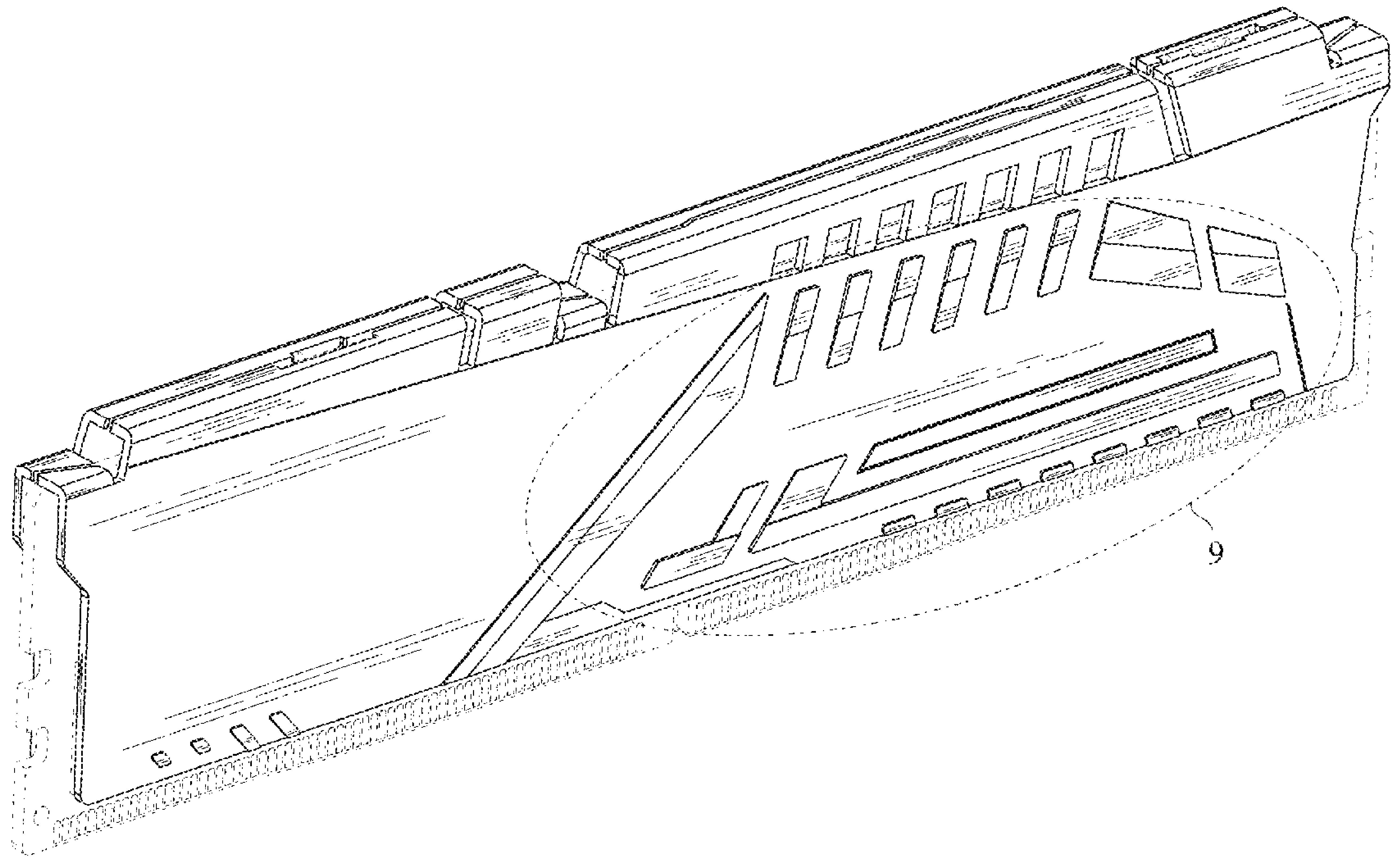
DESCRIPTION

FIG. **1** is a perspective view of a heat sink for memory module of the claimed design;
FIG. **2** is another perspective view of FIG. **1**;
FIG. **3** is a front elevational view of FIG. **1**;
FIG. **4** is a rear elevational view of FIG. **1**;
FIG. **5** is a left side elevational view of FIG. **1**;
FIG. **6** is a right side elevational view of FIG. **1**;
FIG. **7** is a top plan view of FIG. **1**;
FIG. **8** is a bottom plan view of FIG. **1**; and,
FIG. **9** is an enlarged view illustrating the details of the dot-dash area "**9**" shown in FIG. **1**.

The broken lines in the drawings depict portions of the heat sink for memory modul that form no part of the claimed design.

The dot-dash lines in the figures represent the boundaries of the enlarged areas in which the dot-dash lines form no part of the claimed design.

1 Claim, 9 Drawing Sheets



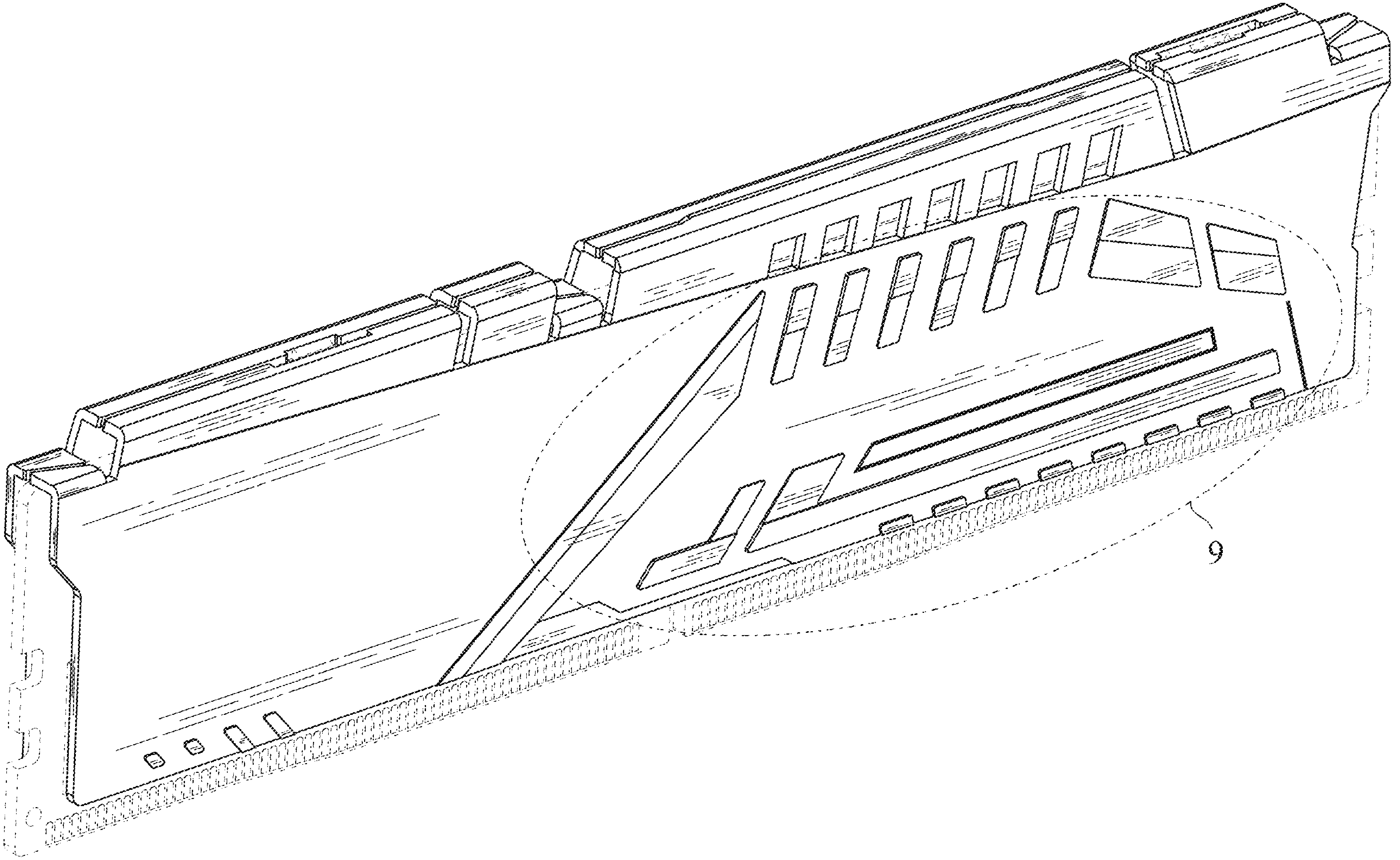


FIG. 1

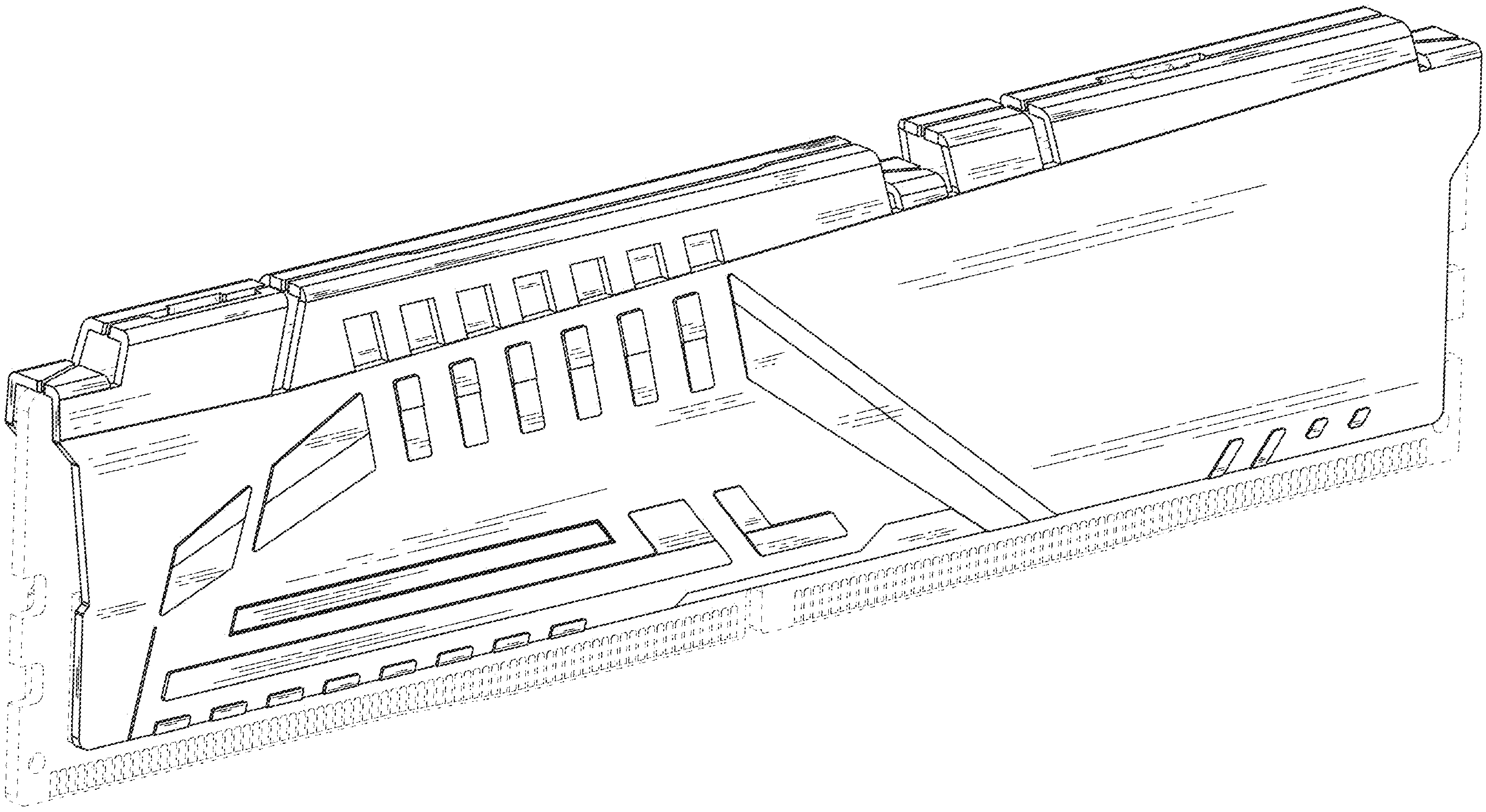


FIG. 2

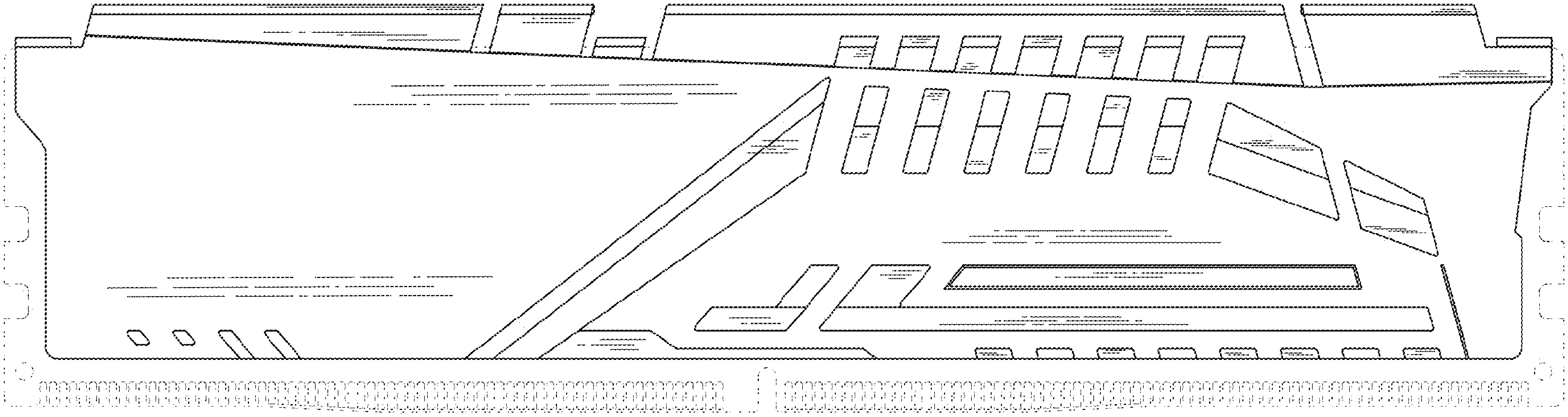


FIG. 3

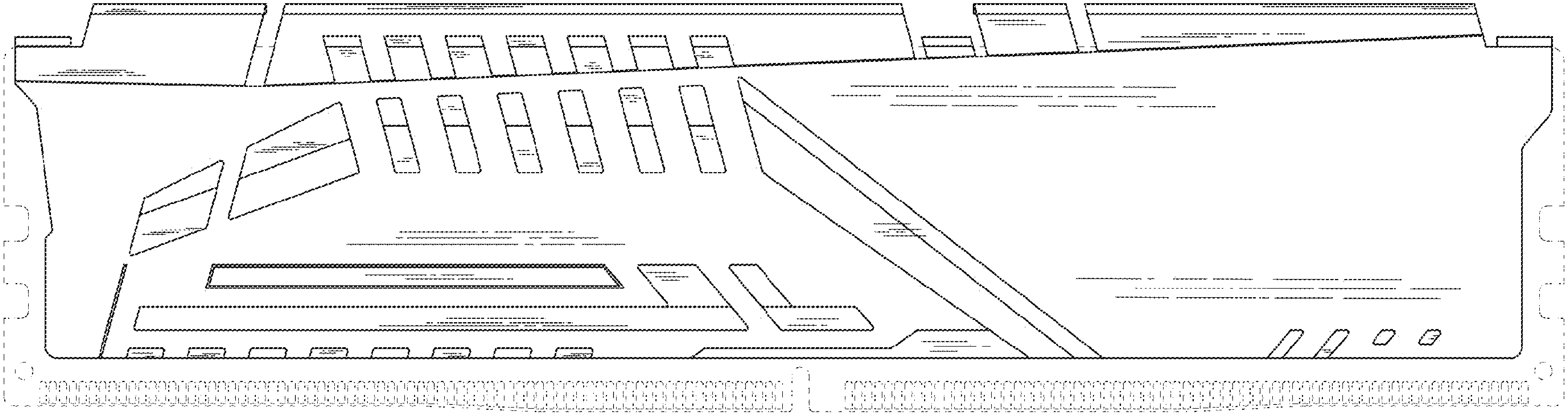


FIG. 4

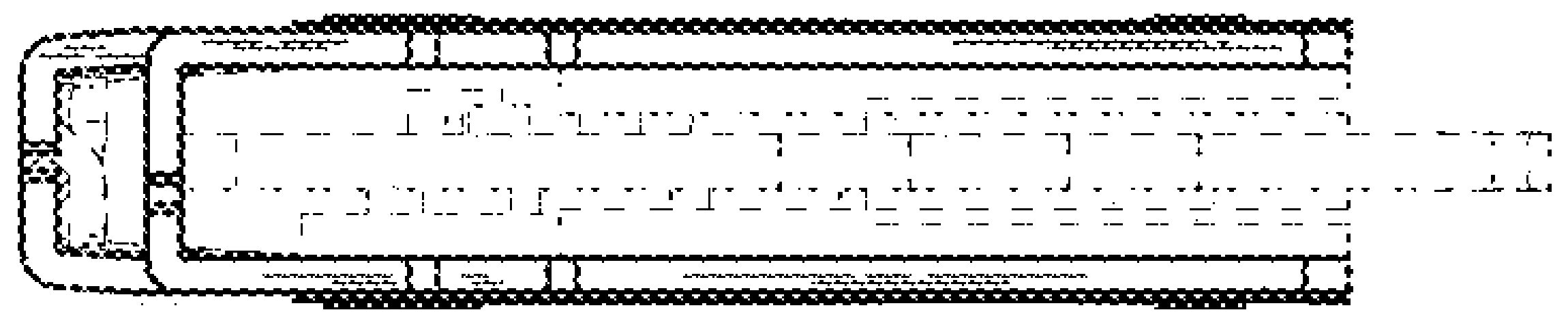


FIG. 5

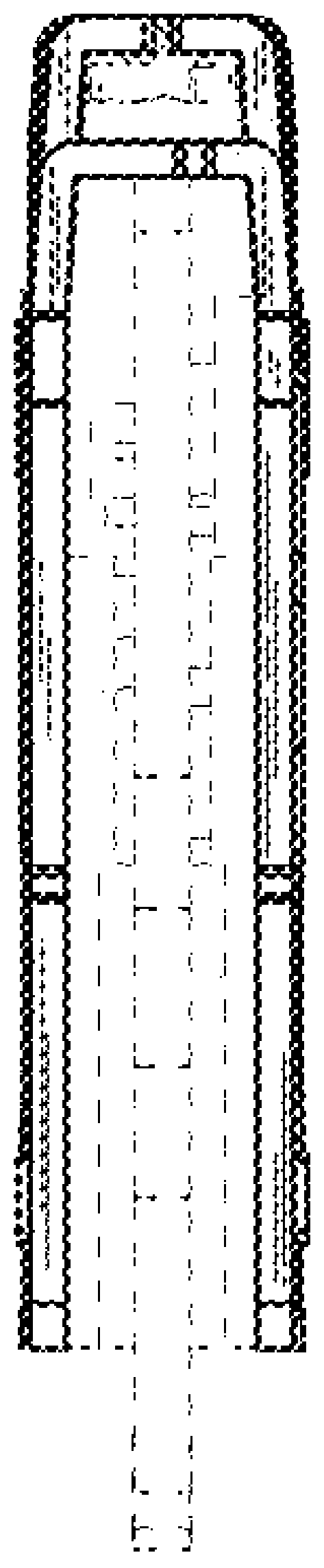


FIG. 6

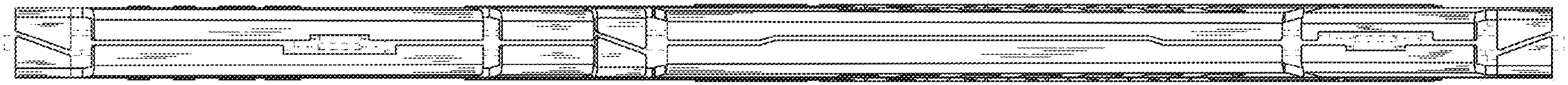


FIG. 7

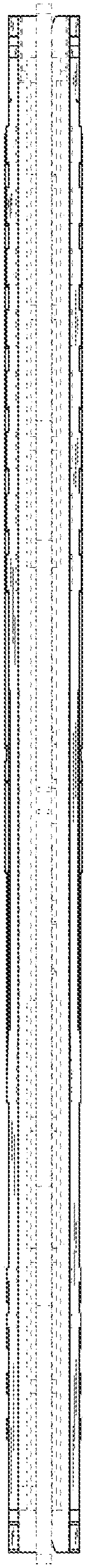


FIG. 8

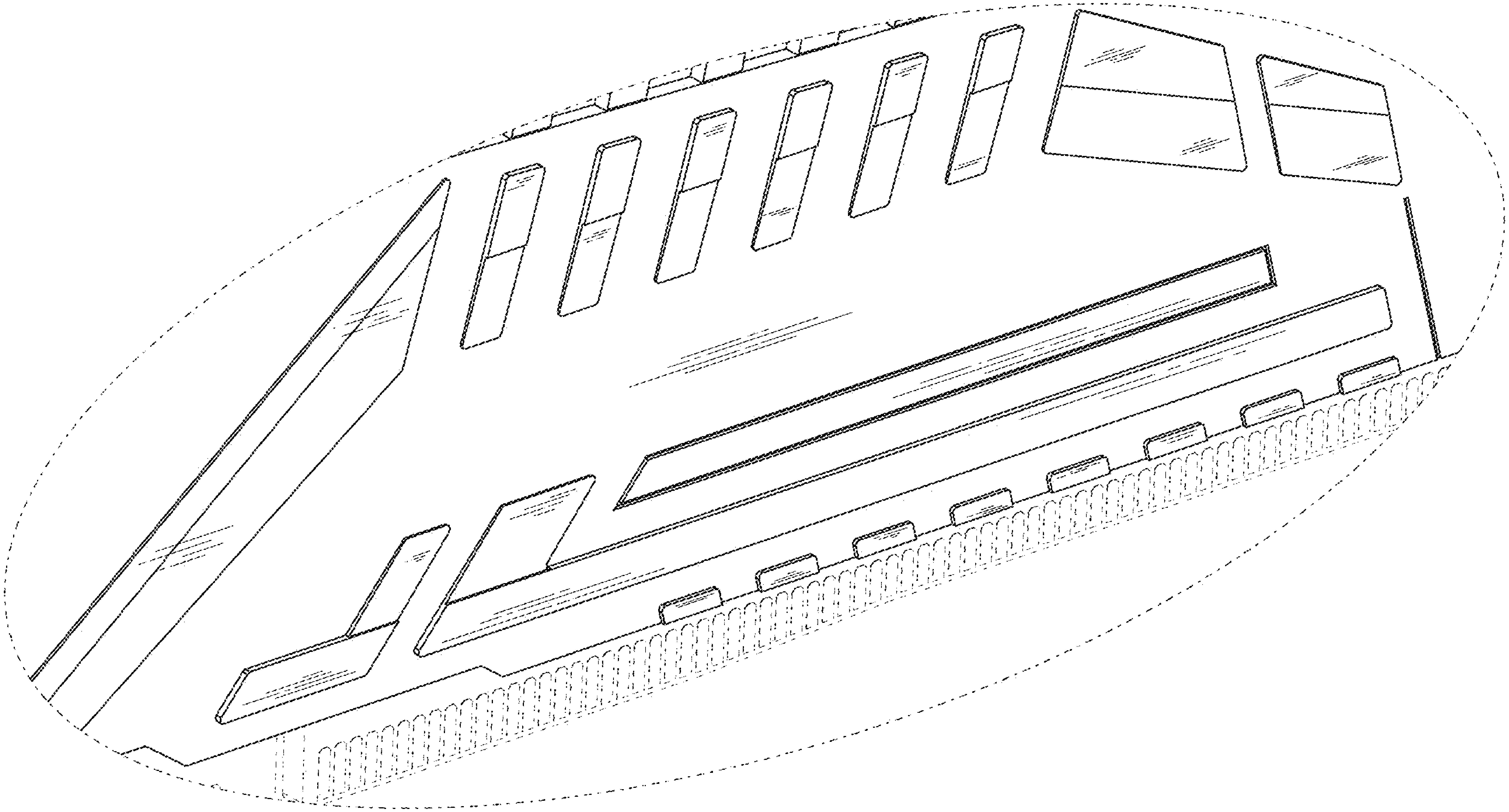


FIG. 9